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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, PWM, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc715-04i-so

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TABLE 4-2: PIC16C715 SPECIAL FUNCTION REGISTER SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR, PER	Value on all other resets (3)
Bank 0	Bank 0										
00h ⁽¹⁾	INDF	Addressing	this location	register)	0000 0000	0000 0000					
01h	TMR0	Timer0 mod	dule's register	r						xxxx xxxx	uuuu uuuu
02h ⁽¹⁾	PCL	Program Co	ounter's (PC)	Least Signif	ficant Byte					0000 0000	0000 0000
03h ⁽¹⁾	STATUS	IRP ⁽⁴⁾	RP1 ⁽⁴⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
04h ⁽¹⁾	FSR	Indirect data	a memory ad	dress pointe	er					xxxx xxxx	uuuu uuuu
05h	PORTA	_	_	_	PORTA Dat	a Latch whe	n written: PO	RTA pins wh	en read	x 0000	u 0000
06h	PORTB	PORTB Da	ta Latch whe	n written: PC	RTB pins wl	nen read				xxxx xxxx	uuuu uuuu
07h	_	Unimpleme	nted							_	_
08h	_	Unimpleme	nted							_	_
09h	_	Unimpleme	nted							_	_
0Ah ^(1,2)	PCLATH	_	_	_	Write Buffer	r for the uppe	er 5 bits of the	e Program C	ounter	0 0000	0 0000
0Bh ⁽¹⁾	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	_	ADIF	_	_	_	_	_	_	-0	-0
0Dh	_	Unimpleme	nted							_	_
0Eh	_	Unimpleme	nted							_	_
0Fh	_	Unimpleme	nted							_	_
10h	_	Unimpleme	nted							_	_
11h	_	Unimpleme	nted							_	_
12h	_	Unimpleme	nted							_	_
13h	_	Unimpleme	nted							_	_
14h	_	Unimpleme	nted							_	_
15h	_	Unimpleme	nted							_	_
16h	_	Unimpleme	nted							_	_
17h	_	Unimpleme	nted							_	_
18h	_	Unimpleme	nted							_	_
19h	_	Unimpleme	nted							_	_
1Ah	_	Unimpleme	nted							_	_
1Bh	_	Unimpleme	nted							_	_
1Ch	_	Unimpleme	Unimplemented —								_
1Dh	_	Unimpleme	nted							_	_
1Eh	ADRES	A/D Result	Register							xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	_	ADON	0000 00-0	0000 00-0

Legend: x = unknown, u = unchanged, q = value depends on condition, -= unimplemented read as '0'. Shaded locations are unimplemented, read as '0'.

- Note 1: These registers can be addressed from either bank.
 - 2: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<12:8> whose contents are transferred to the upper byte of the program counter.
 - 3: Other (non power-up) resets include external reset through $\overline{\text{MCLR}}$ and Watchdog Timer Reset.
 - 4: The IRP and RP1 bits are reserved on the PIC16C715, always maintain these bits clear.

4.2.2.2 OPTION REGISTER

710 71 711 715 Applicable Devices

The OPTION register is a readable and writable register which contains various control bits to configure the TMR0/WDT prescaler, the External INT Interrupt, TMR0, and the weak pull-ups on PORTB.

Note: To achieve a 1:1 prescaler assignment for the TMR0 register, assign the prescaler to the Watchdog Timer by setting bit PSA (OPTION<3>).

FIGURE 4-8: **OPTION REGISTER (ADDRESS 81h, 181h)**

R/	W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
RE	3PU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0
bit7								bit0

= Readable bit W = Writable bit

U = Unimplemented bit, read as '0' - n = Value at POR reset

- bit 7: RBPU: PORTB Pull-up Enable bit
 - 1 = PORTB pull-ups are disabled
 - 0 = PORTB pull-ups are enabled by individual port latch values
- INTEDG: Interrupt Edge Select bit bit 6:
 - 1 = Interrupt on rising edge of RB0/INT pin
 - 0 = Interrupt on falling edge of RB0/INT pin
- bit 5: T0CS: TMR0 Clock Source Select bit
 - 1 = Transition on RA4/T0CKI pin
 - 0 = Internal instruction cycle clock (CLKOUT)
- T0SE: TMR0 Source Edge Select bit bit 4:
 - 1 = Increment on high-to-low transition on RA4/T0CKI pin
 - 0 = Increment on low-to-high transition on RA4/T0CKI pin
- bit 3: PSA: Prescaler Assignment bit
 - 1 = Prescaler is assigned to the WDT
 - 0 = Prescaler is assigned to the Timer0 module
- bit 2-0: PS2:PS0: Prescaler Rate Select bits

Bit Value	TMR0 Rate	WDT Rate
000 001 010 011 100 101	1:2 1:4 1:8 1:16 1:32 1:64 1:128	1:1 1:2 1:4 1:8 1:16 1:32 1:64
111	1 : 256	1 : 128

5.3 <u>I/O Programming Considerations</u>

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched to an output, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. \mathtt{BCF} , \mathtt{BSF} , etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-3 shows the effect of two sequential readmodify-write instructions on an I/O port.

EXAMPLE 5-3: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT settings: PORTB<7:4> Inputs
                        PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
                     PORT latch PORT pins
 BCF PORTB, 7
                   ; 01pp pppp
                                  11pp pppp
 BCF PORTB, 6
                   ; 10pp pppp
                                  11pp pppp
 BSF STATUS, RPO
  BCF TRISB, 7
                   ; 10pp pppp
                                  11pp pppp
 BCF TRISB, 6
                   ; 10pp pppp
                                  10pp pppp
```

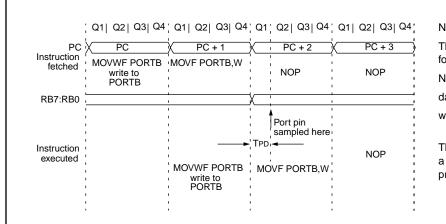
;Note that the user may have expected the ;pin values to be 00pp ppp. The 2nd BCF ;caused RB7 to be latched as the pin value ;(high).

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-6). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

FIGURE 5-6: SUCCESSIVE I/O OPERATION



Note:

This example shows a write to PORTB followed by a read from PORTB.

Note that:

data setup time = (0.25Tcy - TpD)

where TcY = instruction cycle
TPD = propagation delay

Therefore, at higher clock frequencies, a write followed by a read may be problematic.

FIGURE 8-2: CONFIGURATION WORD, PIC16C710/711

CONFIG CP0 CP0 CP0 CP0 CP0 CP0 BODEN CP0 CP0 PWRTE WDTE FOSC1 FOSC0 Register: Address 2007h bit13 bit 13-7 CP0: Code protection bits (2) 5-4: 1 = Code protection off 0 = All memory is code protected, but 00h - 3Fh is writable BODEN: Brown-out Reset Enable bit (1) bit 6: 1 = BOR enabled 0 = BOR disabled PWRTE: Power-up Timer Enable bit (1) bit 3: 1 = PWRT disabled 0 = PWRT enabled WDTE: Watchdog Timer Enable bit bit 2: 1 = WDT enabled 0 = WDT disabled bit 1-0: FOSC1:FOSC0: Oscillator Selection bits 11 = RC oscillator 10 = HS oscillator 01 = XT oscillator 00 = LP oscillator Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit PWRTE. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled. 2: All of the CP0 bits have to be given the same value to enable the code protection scheme listed.

FIGURE 8-3: CONFIGURATION WORD, PIC16C715

CP1	CP0	CP1	CP0	CP1	CP0	MPEEN	BODEN	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0	Register:	CONFIG
bit13													bit0	Address	2007h
bit 13- 5-	4: 11 10 01		de prot ber hal ber 3/4	ection f of pro th of p	off ogram rogran	memory n memor	code pro								
bit 7:	1	= Mem	ory Pa	rity Ch	néckino	or Enabl g is enab g is disal	led								
bit 6:	1	BODEN: Brown-out Reset Enable bit ⁽¹⁾ 1 = BOR enabled 0 = BOR disabled													
bit 3:	1	WRTE: = PWR = PWR	T disa	bled	mer Eı	nable bit	(1)								
bit 2:	1	DTE: V = WDT = WDT	enabl	eď	ner En	able bit									
bit 1-0	11 10 01	DSC1:I L = RC) = HS L = XT) = LP	oscilla oscilla oscilla	ator itor tor	illator (Selectior	bits								
Note	Er	nsure t	he Pov	ver-up	Timer	is enabl	ed anytin	ne Brov	wn-out	Reset is	enable	d.		e value of bit in	PWRTE.

FIGURE 8-11: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 1

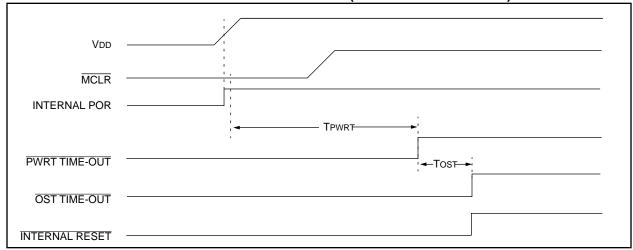


FIGURE 8-12: TIME-OUT SEQUENCE ON POWER-UP (MCLR NOT TIED TO VDD): CASE 2

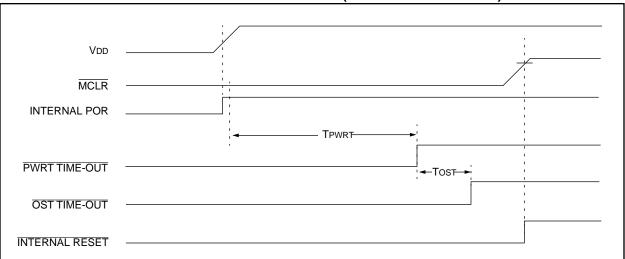


FIGURE 8-13: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD)

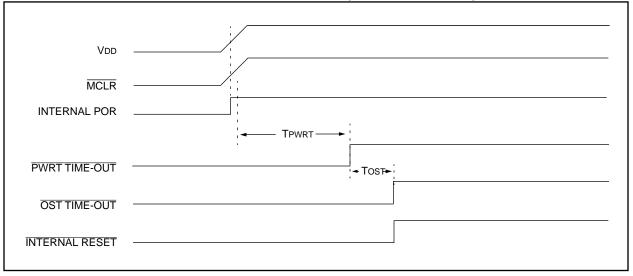
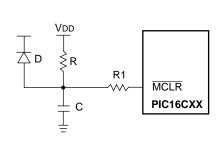
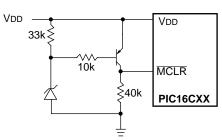


FIGURE 8-14: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



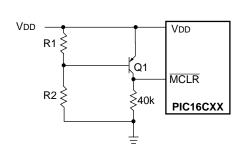
- Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.
 - 2: $R < 40 \text{ k}\Omega$ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.
 - 3: $R1 = 100\Omega$ to 1 k Ω will limit any current flowing into \overline{MCLR} from external capacitor C in the event of \overline{MCLR} /VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

FIGURE 8-15: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



- Note 1: This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.
 - 2: Internal brown-out detection on the PIC16C710/711/715 should be disabled when using this circuit.
 - Resistors should be adjusted for the characteristics of the transistor.

FIGURE 8-16: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \bullet \frac{R1}{R1 + R2} = 0.7V$$

- 2: Internal brown-out detection on the PIC16C710/711/715 should be disabled when using this circuit.
- 3: Resistors should be adjusted for the characteristics of the transistor.

CLRF	Clear f						
Syntax:	[label] C	LRF f					
Operands:	$0 \le f \le 12$	27					
Operation:	$\begin{array}{c} 00h \rightarrow (f) \\ 1 \rightarrow Z \end{array}$)					
Status Affected:	Z						
Encoding:	00	0001	1fff	ffff			
Description:	The contents of register 'f' are cleared and the Z bit is set.						
Words:	1						
Cycles:	1						
Q Cycle Activity:	Q1	Q2	Q3	Q4			
	Decode	Read register 'f'	Process data	Write register 'f'			
Example	CLRF	FLAG	G_REG				
	Before Instruction FLAG_REG = 0x5A						
	After Inst	ruction					

 $FLAG_REG = 0x00$

CLRW	Clear W						
Syntax:	[label]	CLRW					
Operands:	None						
Operation:	$\begin{array}{c} 00h \rightarrow (V \\ 1 \rightarrow Z \end{array}$	V)					
Status Affected:	Z						
Encoding:	00	0001	0xxx	xxxx			
Description:	W register is cleared. Zero bit (Z) is set.						
Words:	1						
Cycles:	1						
Q Cycle Activity:	Q1	Q2	Q3	Q4			
	Decode	NOP	Process data	Write to W			
Example	CLRW						
	Before In	struction	1				
	After Inst	W =	0x5A				
		W = Z =	0x00 1				

CLRWDT	Clear Wa	tchdog	Timer					
Syntax:	[label]	CLRWD	Т					
Operands:	None							
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{\text{TO}}$ 1 → $\overline{\text{PD}}$							
Status Affected:	TO, PD							
Encoding:	00	0000	0110	0100				
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits TO and PD are set.							
Words:	1							
Cycles:	1							
Q Cycle Activity:	Q1	Q2	Q3	Q4				
	Decode	NOP	Process data	Clear WDT Counter				
Example	CLRWDT							
	Before In	WDT cou		?				
	WDT counter = 0x00							
		WDT pres	scaler= =	0				
		PD	=	1				

GOTO	Uncondi	tional B	ranch			INCF	Increme	nt f			
Syntax:	[label]	GOTO	k		•	Syntax:	[label]	[label] INCF f,d			
Operands:	$0 \le k \le 20$	047				Operands:	$0 \le f \le 127$				
Operation:	$k \rightarrow PC <$					•	$d \in [0,1]$				
	PCLATH-	<4:3> →	PC<12:1	1>		Operation:	$(f) + 1 \rightarrow (dest)$				
Status Affected:	None					Status Affected:	Z				
Encoding:	10	1kkk	kkkk	kkkk]	Encoding:	0.0	1010	dfff	ffff	
Description:	otion: GOTO is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two cycle instruction.				-	Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.				
Words:	1					Words:	1				
Cycles:	2					Cycles:	1				
Q Cycle Activity:	Q1	Q2	Q3	Q4		Q Cycle Activity:	Q1	Q2	Q3	Q4	
1st Cycle	Decode	Read literal 'k'	Process data	Write to PC			Decode	Read register 'f'	Process data	Write to dest	
2nd Cycle	NOP	NOP	NOP	NOP							
			•		•	Example	INCF	CNT,	1		
Example	GOTO T	HERE					Before In	struction	1		
	After Instruction						CNT	= 0xFf	F		
		PC =	Address	THERE				Z	= 0		
							After Ins				
								CNT	= 0x00)	

IORWF	Inclusive	OR W	with f				
Syntax:	[label]	IORWF	f,d				
Operands:	$0 \le f \le 12$ $d \in [0,1]$	27					
Operation:	(W) .OR. (f) \rightarrow (dest)						
Status Affected:	Z						
Encoding:	00	0100	dfff	ffff			
Description:	Inclusive OR the W register with register 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.						
Words:	1						
Cycles:	1						
Q Cycle Activity:	Q1	Q2	Q3	Q4			
	Decode	Read register 'f'	Process data	Write to dest			
Example	IORWF		RESULT,	0			
		struction RESULT W					
	After Inst	ruction					
		RESULT W	= 0x13 = 0x93				

Move Literal to W								
[label]	MOVLW	/ k						
$0 \le k \le 2$	55							
$k \to (W)$								
None								
11 00xx kkkk kkkk								
The eight bit literal 'k' is loaded into W register. The don't cares will assemble as 0's.								
1								
1								
Q1	Q2	Q3	Q4					
Decode	Read literal 'k'	Process data	Write to W					
,		0x5A						

MOVF	Move f						
Syntax:	[label]	MOVF	f,d				
Operands:	$0 \le f \le 127$ $d \in [0,1]$						
Operation:	$(f) \rightarrow (dest)$						
Status Affected:	Z						
Encoding:	0.0	1000	dfff	ffff			
Description:	The contents of register f is moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.						
Words:	1						
Cycles:	1						
Q Cycle Activity:	Q1	Q2	Q3	Q4			
	Decode	Read register 'f'	Process data	Write to dest			
Example	MOVF	FSR,	0				
	After Instruction W = value in FSR register						

Z = 1

MOVWF	Move W	to f		
Syntax:	[label]	MOVWI	F f	
Operands:	$0 \le f \le 12$	27		
Operation:	$(W) \rightarrow (f)$)		
Status Affected:	None			
Encoding:	00	0000	1fff	ffff
Description:	Move data	from W r	egister to	register
Words:	1			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process data	Write register 'f'
Example	MOVWF	OPTIC	ON_REG	
	After Inst	OPTION W	= 0xFi = 0x4F	=

11.5 <u>Timing Diagrams and Specifications</u>

FIGURE 11-2: EXTERNAL CLOCK TIMING

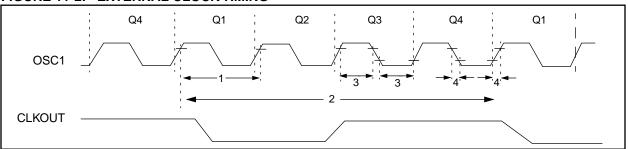


TABLE 11-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC		4	MHz	XT osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	_	-	ns	XT osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
		Oscillator Period	250	_	–	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	250	ns	HS osc mode (-20)
			5		_	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200		DC	ns	Tcy = 4/Fosc
3	TosL,	External Clock in (OSC1) High	50	_	_	ns	XT oscillator
	TosH	or Low Time	2.5	_	_	μs	LP oscillator
			10	_	_	ns	HS oscillator
4	TosR,	External Clock in (OSC1) Rise	_	_	25	ns	XT oscillator
	TosF	or Fall Time	_	_	50	ns	LP oscillator
		The state of the s	_	—	15	ns	HS oscillator

[†] Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C710/711.

FIGURE 12-22: TYPICAL XTAL STARTUP
TIME vs. Vdd (LP MODE, 25°C)

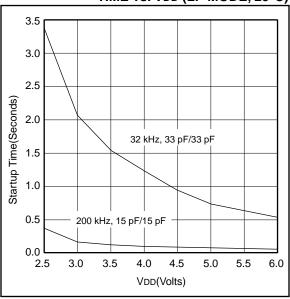


FIGURE 12-23: TYPICAL XTAL STARTUP TIME vs. VdD (HS MODE, 25° C)

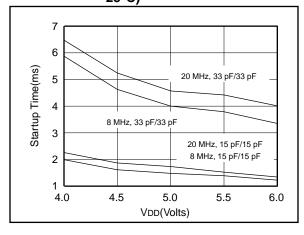


FIGURE 12-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

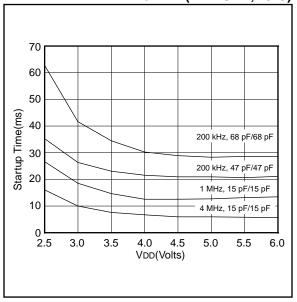


TABLE 12-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2	
LP	32 kHz	33 pF	33 pF	
	200 kHz	15 pF	15 pF	
XT	200 kHz	47-68 pF	47-68 pF	
	1 MHz	15 pF	15 pF	
	4 MHz	15 pF	15 pF	
HS	4 MHz	15 pF	15 pF	
	8 MHz	15-33 pF	15-33 pF	
	20 MHz	15-33 pF	15-33 pF	
	•			
Crystals Used				
32 kHz	Epson C-00	01R32.768K-A	± 20 PPM	
200 kHz	STD XTL 2	STD XTL 200.000KHz		
1 MHz	ECS ECS-	ECS ECS-10-13-1		
4 MHz	ECS ECS-4	ECS ECS-40-20-1		
8 MHz	EPSON CA	EPSON CA-301 8.000M-C		
20 MHz	EPSON CA	A-301 20.000M-C	± 30 PPM	

TABLE 13-6: A/D CONVERTER CHARACTERISTICS:

PIC16C715-04 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C715-10 (COMMERCIAL, INDUSTRIAL, EXTENDED) PIC16C715-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	NR	Resolution	_	_	8-bits	_	VREF = VDD, VSS ≤ AIN ≤ VREF
	NINT	Integral error	_	_	less than ±1 LSb	_	VREF = VDD, VSS ≤ AIN ≤ VREF
	NDIF	Differential error	_	_	less than ±1 LSb	_	VREF = VDD, VSS ≤ AIN ≤ VREF
	NFS	Full scale error	_	_	less than ±1 LSb	_	VREF = VDD, VSS ≤ AIN ≤ VREF
	Noff	Offset error	_	_	less than ±1 LSb	_	VREF = VDØ, VSS \$ AIN ≤ VREF
	_	Monotonicity	_	guaranteed	_	_	VSS & AIN & VREF
	VREF	Reference voltage	2.5V	_	VDD + 0.3	V/	
	Vain	Analog input voltage	Vss - 0.3	_	VREF + 0.3	V\	
	Zain	Recommended impedance of analog voltage source	_	_	10.0	kΩ	
	IAD	A/D conversion current (VDD)	_	180		ptA .	Average current consumption when A/D is on. (Note 1)
	IREF	VREF input current (Note 2)	_		1 10	mA μA	During sampling All other times

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.
 - 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

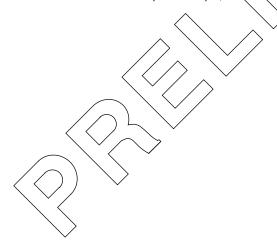


FIGURE 14-16: TYPICAL IDD vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

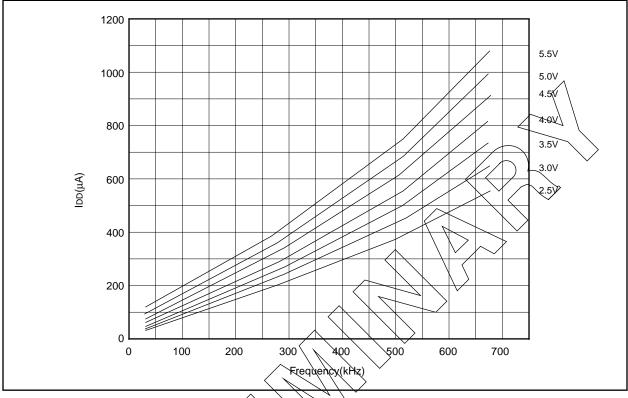
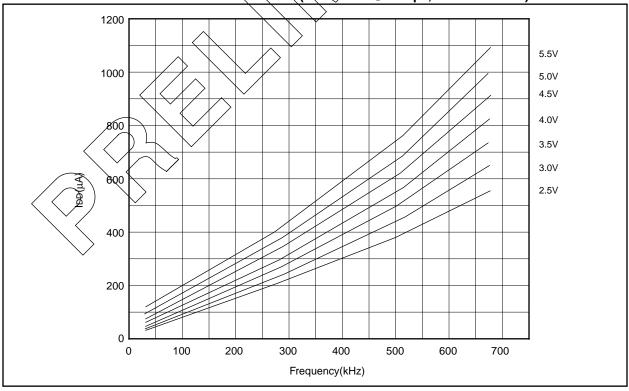


FIGURE 14-17: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



Applicable Devices 710 71 711 715

15.3 DC Characteristics: PIC16C71-04 (Commercial, Industrial)

PIC16C71-20 (Commercial, Industrial) PIC16LC71-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated)

OOperating temperature $0^{\circ}C$ $\leq TA \leq +70^{\circ}C$ (commercial)

DC CHARACTERISTICS $-40^{\circ}\text{C} \leq \text{TA} \leq +85^{\circ}\text{C} \text{ (industrial)}$

Operating voltage $\ensuremath{\text{VDD}}$ range as described in DC spec Section 15.1

and Section 15.2.

Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions
No.				†			
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		Vss	-	0.15V	V	For entire VDD range
D031	with Schmitt Trigger buffer		Vss	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2Vdd	V	
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3Vdd	V	Note1
	Input High Voltage						
	I/O ports (Note 4)	VIH		-			
D040	with TTL buffer		2.0	-	Vdd	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD		For entire VDD range
D041	with Schmitt Trigger buffer		0.85VDD	-	Vdd		For entire VDD range
D042	MCLR, RB0/INT		0.85VDD	-	Vdd	V	
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	Vdd	V	
D070	PORTB weak pull-up current	IPURB	50	250	†400	μΑ	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	lı∟	-	-	±1	•	Vss ≤ VPIN ≤ VDD, Pin at hi- impedance
D061	MCLR, RA4/T0CKI		-	-	±5	μΑ	Vss ≤ Vpin ≤ Vdd
D063	OSC1		-	-	±5	μΑ	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						-
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	Vон	VDD - 0.7	-	-	V	IOH = -3.0mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	-	-	V	IOH = -1.3mA, VDD = 4.5V, -40°C to +85°C
D130*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin

[†] Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- 2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3: Negative current is defined as current sourced by the pin.
- 4: PIC16C71 Rev. "Ax" INT pin has a TTL input buffer. PIC16C71 Rev. "Bx" INT pin has a Schmitt Trigger input buffer.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC16C71 be driven with external clock in RC mode.

FIGURE 16-12: TYPICAL IDD Vs. FREQ (EXT CLOCK, 25°C)

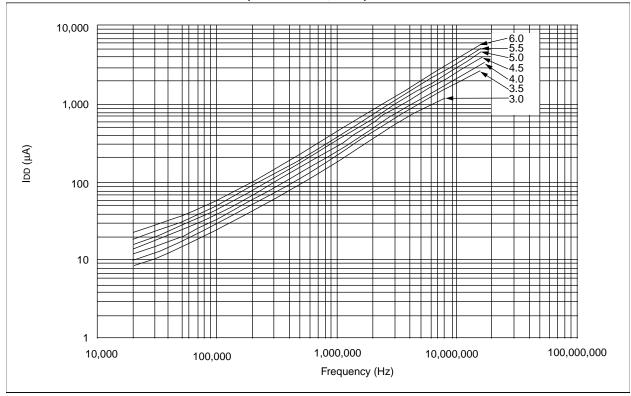


FIGURE 16-13: MAXIMUM, IDD vs. FREQ (EXT CLOCK, -40° TO +85°C)

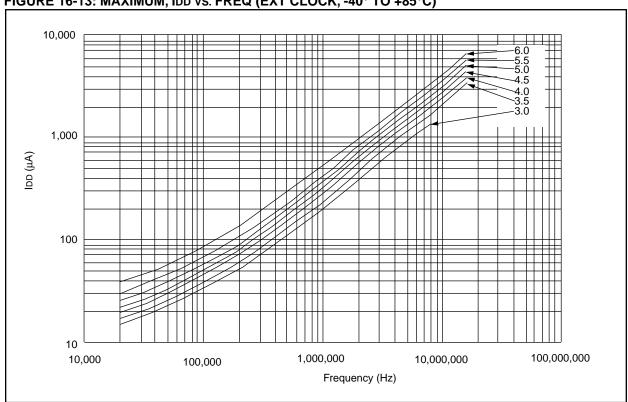


FIGURE 16-14: MAXIMUM IDD VS. FREQ WITH A/D OFF (EXT CLOCK, -55° TO +125°C)

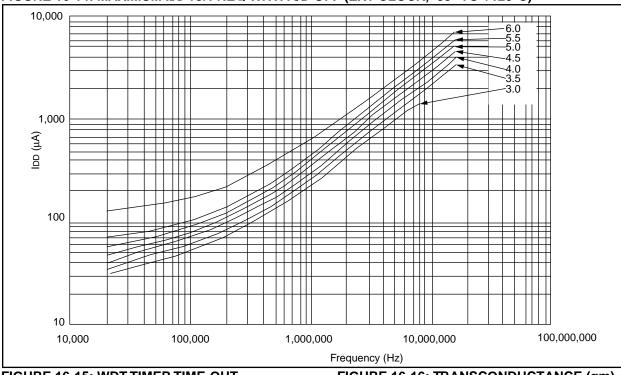


FIGURE 16-15: WDT TIMER TIME-OUT PERIOD vs. VDD

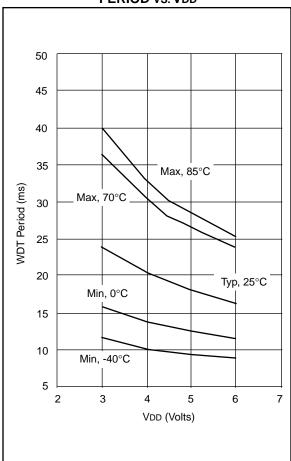
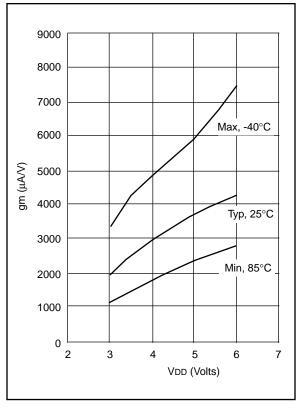


FIGURE 16-16: TRANSCONDUCTANCE (gm)
OF HS OSCILLATOR vs. VDD



APPENDIX A:

The following are the list of modifications over the PIC16C5X microcontroller family:

- Instruction word length is increased to 14-bits.
 This allows larger page sizes both in program memory (1K now as opposed to 512 before) and register file (68 bytes now versus 32 bytes before).
- A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
- 3. Data memory paging is redefined slightly. STATUS register is modified.
- Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW.
 Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
- OPTION and TRIS registers are made addressable.
- Interrupt capability is added. Interrupt vector is at 0004h.
- 7. Stack size is increased to 8 deep.
- 8. Reset vector is changed to 0000h.
- Reset of all registers is revisited. Five different reset (and wake-up) types are recognized. Registers are reset differently.
- Wake up from SLEEP through interrupt is added.
- 11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
- 12. PORTB has weak pull-ups and interrupt on change feature.
- 13. T0CKI pin is also a port pin (RA4) now.
- 14. FSR is made a full eight bit register.
- 15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, Vss, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
- 16. PCON status register is added with a Power-on Reset status bit (POR).
- Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
- 18. Brown-out protection circuitry has been added. Controlled by configuration word bit BODEN. Brown-out reset ensures the device is placed in a reset condition if VDD dips below a fixed setpoint.

APPENDIX B: COMPATIBILITY

To convert code written for PIC16C5X to PIC16CXX, the user should take the following steps:

- Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
- 2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
- 3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
- Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
- 5. Change reset vector to 0000h.

TO bit	
TRISA Register	
TRISB Register	
Two's Complement	
U	
Upward Compatibility	3
UV Erasable Devices	
W	
W Register	
ALU	
Wake-up from SLEEP	
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